

3D integration and Advanced Packaging Programs at SEMICON West

I-Micronews

The SEMI Advanced Packaging Committee, chaired by Bill Chen, ASE Fellow, has been hard at work making sure all bases are covered in this expanding market sector from 3D integration, heterogeneous integration of MEMS and sensors to the latest in 'contemporary' packaging and wafer-level packaging (WLP) processes. In fact, so much ground to cover called for the expansion of the original time slots.

Divided on three different stages over two days, this year's programs will follow a keynote/panel discussion format with representatives from across the supply chain assembled to discuss challenges and solutions for each focus area.

Heterogeneous Integration with MEMs & Sensors (Tues. July 12 2:00pm-4:30p)

[SOURCE](#) [1]

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http://www.mdtmag.com/news/2011/05/3d-integration-and-advanced-packaging-programs-semicon-west?qt-recent_content=0

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[1] <http://www.i-micronews.com/lectureArticle.asp?id=6952>